



H-1013

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

T. ISHIDA et al

Serial No. 09/964,484

Examiner: A. Williams

Filed: September 28, 2001

Group Art Unit: 2826

For: A SEMICONDUCTOR DEVICE HAVING STACKED SEMICONDUCTOR
CHIPS SEALED WITH A RESIN SEAL MEMBER (As Amended)

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed July 18, 2003,
please amend the above-identified application as follows. A
Petition and fee for a one-month Extension of Time accompanies
this response.

REMARKS

Claims 1-31 are currently pending in the application.

Priority

Applicants appreciate the Examiner's acknowledgment of
the claim for priority and safe receipt of the certified
foreign priority document.

35 USC §102

Claims 1-31 have been rejected under 35 USC 102(e) as
being anticipated by Ohie. The rejections are traversed as
follows.